

P-Channel Enhancement Mode Power MOSFET

Description

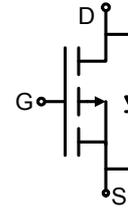
The HM6409 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a load switch or in PWM applications.

General Features

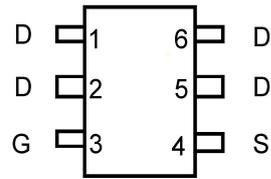
- $V_{DS} = -20V, I_D = -5.0A$
 $R_{DS(ON)} < 75m\Omega @ V_{GS} = -2.5V$
 $R_{DS(ON)} < 52m\Omega @ V_{GS} = -4.5V$
- High power and current handling capability
- Lead free product is acquired
- Surface mount package

Application

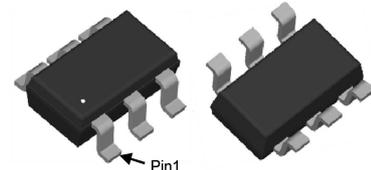
- PWM applications
- Load switch
- Power management



Schematic diagram



Marking and pin Assignment



SOT-23-6L top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|--------|----------------|-----------|------------|------------|
| 6409 | HM6409 | SOT-23-6L | Ø180mm | 8 mm | 3000 units |

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise noted)

| Parameter | Symbol | Limit | Unit | |
|--|----------------|--------------------|------------|---|
| Drain-Source Voltage | V_{DS} | -20 | V | |
| Gate-Source Voltage | V_{GS} | ± 12 | V | |
| Continuous Drain Current | I_D | $T_C = 25^\circ C$ | -5.0 | A |
| | | $T_C = 70^\circ C$ | -3.5 | |
| | | $T_A = 25^\circ C$ | -3 | |
| | | $T_A = 70^\circ C$ | -2.3 | |
| Drain Current -Pulsed (Note 1) | I_{DM} | -15 | A | |
| Maximum Power Dissipation | P_D | 1.7 | W | |
| Operating Junction and Storage Temperature Range | T_J, T_{STG} | -55 To 150 | $^\circ C$ | |

Thermal Characteristic

| | | | |
|--|-----------------|----|--------------|
| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 74 | $^\circ C/W$ |
|--|-----------------|----|--------------|

Electrical Characteristics (T_A=25°C unless otherwise noted)

| Parameter | Symbol | Condition | Min | Typ | Max | Unit |
|---|---------------------|---|-------|------|------|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =-250μA | -20 | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-20V, V _{GS} =0V | - | - | -1 | μA |
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±12V, V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | | | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} , I _D =-250μA | -0.45 | -0.7 | -1.0 | V |
| Drain-Source On-State Resistance | R _{DS(ON)} | V _{GS} =-4.5V, I _D =-5.0A | - | 39 | 52 | mΩ |
| | | V _{GS} =-2.5V, I _D =-3A | - | 58 | 75 | |
| Forward Transconductance | g _{FS} | V _{DS} =-5V, I _D =-2A | 6 | - | - | S |
| Dynamic Characteristics (Note4) | | | | | | |
| Input Capacitance | C _{ISS} | V _{DS} =-4V, V _{GS} =0V, F=1.0MHz | - | 740 | - | PF |
| Output Capacitance | C _{OSS} | | - | 290 | - | PF |
| Reverse Transfer Capacitance | C _{RSS} | | - | 190 | - | PF |
| Switching Characteristics (Note 4) | | | | | | |
| Turn-on Delay Time | t _{d(on)} | V _{DD} =-4V, I _D =-3.3A , R _L =-1.2Ω, V _{GEN} =-4.5V, R _g =1Ω | - | 12 | - | nS |
| Turn-on Rise Time | t _r | | - | 35 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | | - | 30 | - | nS |
| Turn-Off Fall Time | t _f | | - | 10 | - | nS |
| Total Gate Charge | Q _g | V _{DS} =-4V, I _D =-5.0A, V _{GS} =-4.5V | - | 7.8 | - | nC |
| Gate-Source Charge | Q _{gs} | | - | 1.2 | - | nC |
| Gate-Drain Charge | Q _{gd} | | - | 1.6 | - | nC |
| Drain-Source Diode Characteristics | | | | | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V, I _S =-1.6A | - | - | -1.2 | V |
| Diode Forward Current (Note 2) | I _S | | - | - | 1.6 | A |

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production

Typical Electrical and Thermal Characteristics



Figure 1: Switching Test Circuit

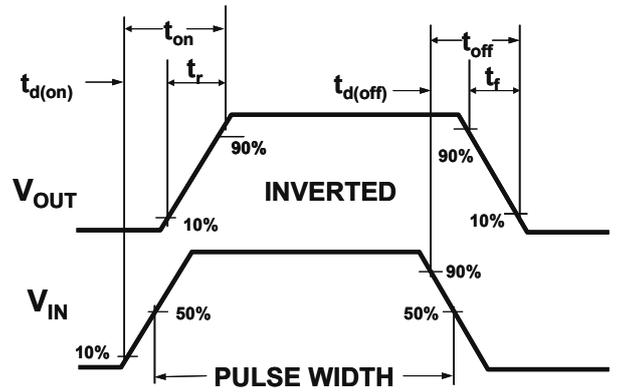
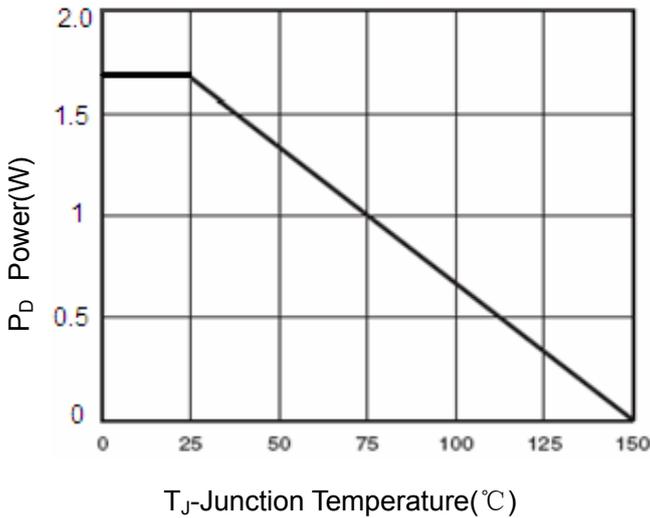
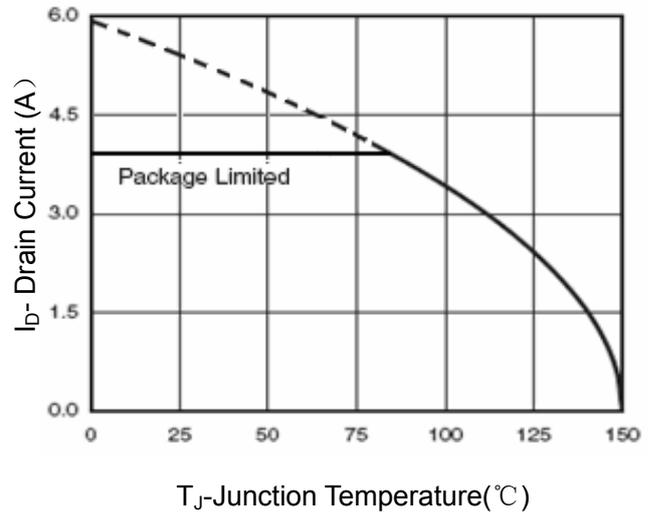


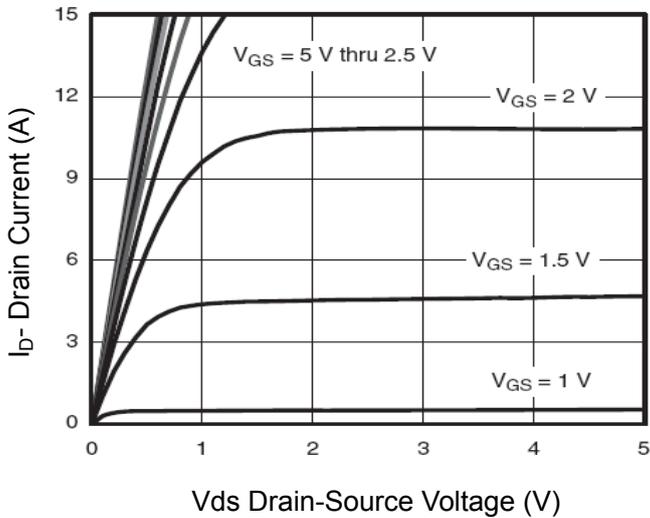
Figure 2: Switching Waveforms



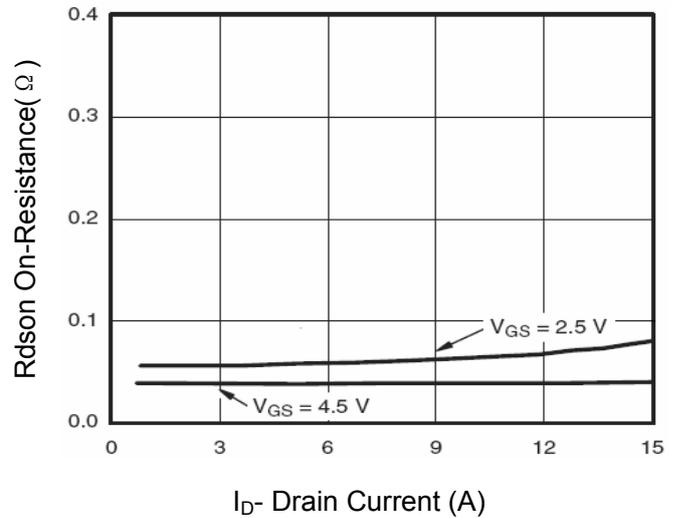
T_J-Junction Temperature(°C)
Figure 3 Power Dissipation



T_J-Junction Temperature(°C)
Figure 4 Drain Current



V_{ds} Drain-Source Voltage (V)
Figure 5 Output Characteristics



I_D- Drain Current (A)
Figure 6 Drain-Source On-Resistance

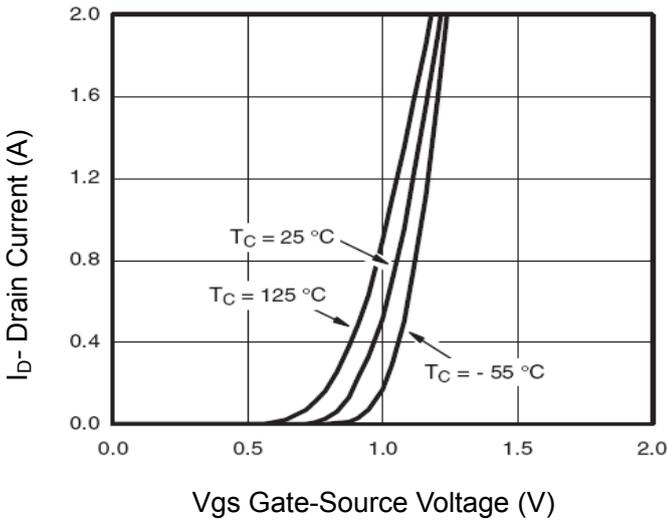


Figure 7 Transfer Characteristics

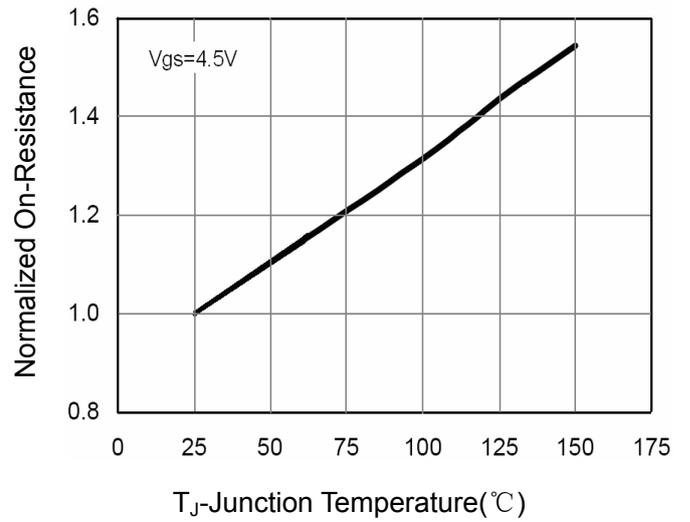


Figure 8 Drain-Source On-Resistance

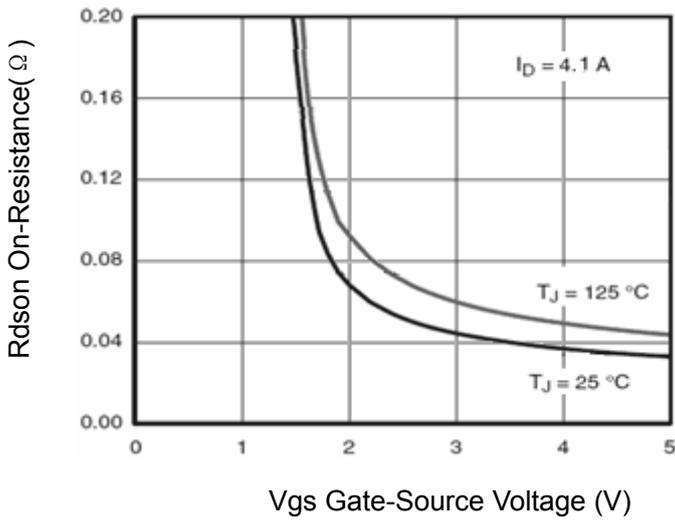


Figure 9 Rdson vs Vgs

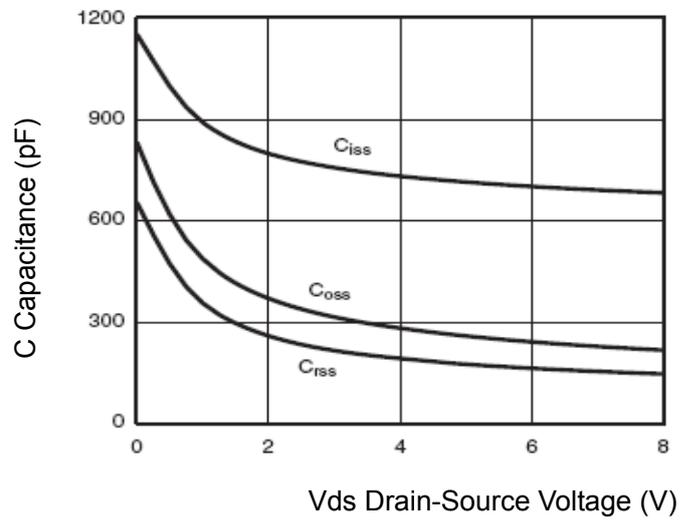


Figure 10 Capacitance vs Vds

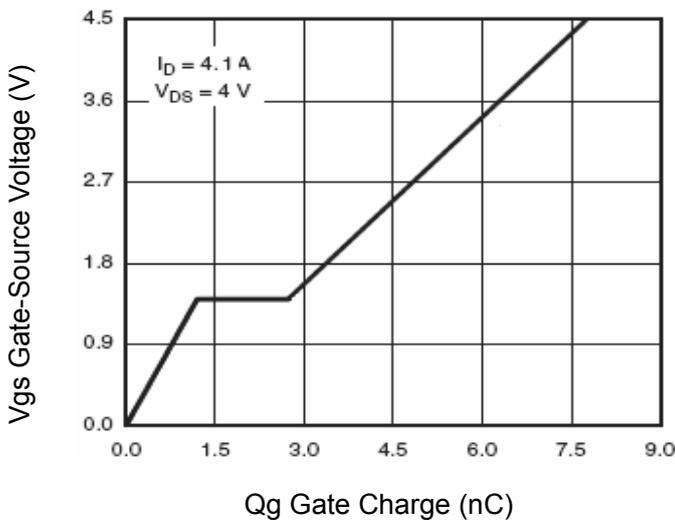


Figure 11 Gate Charge

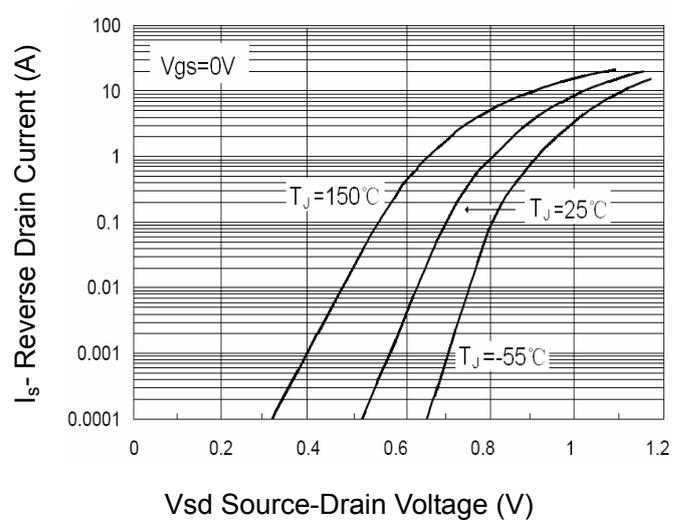


Figure 12 Source- Drain Diode Forward

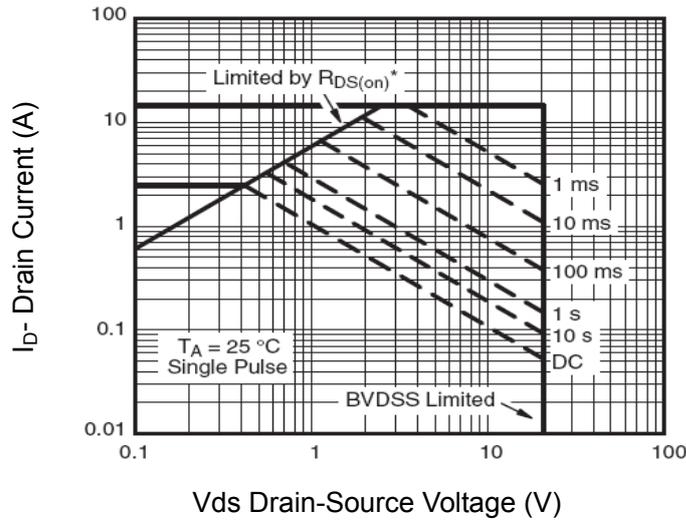


Figure 13 Safe Operation Area

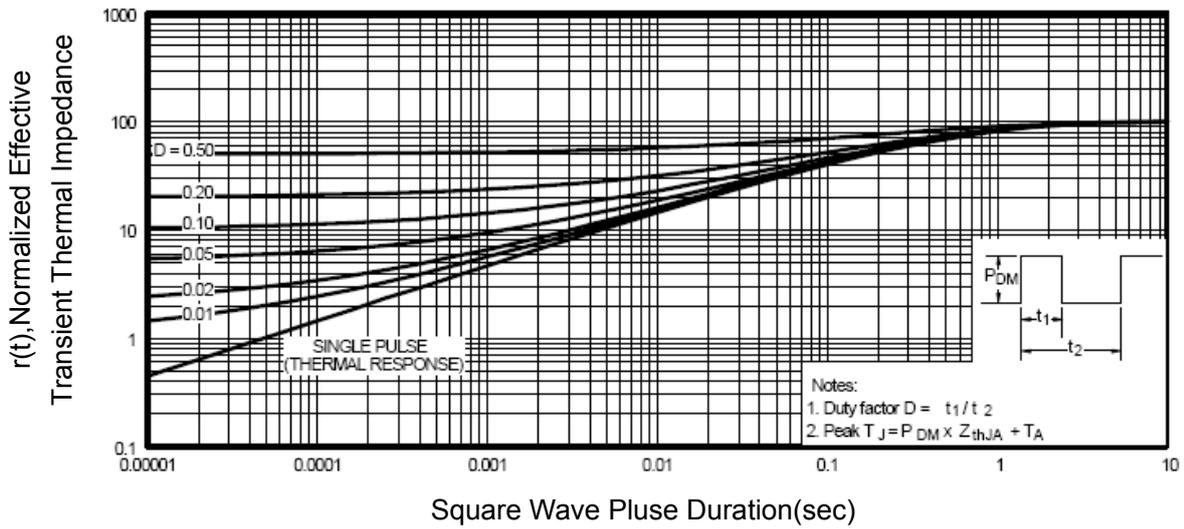
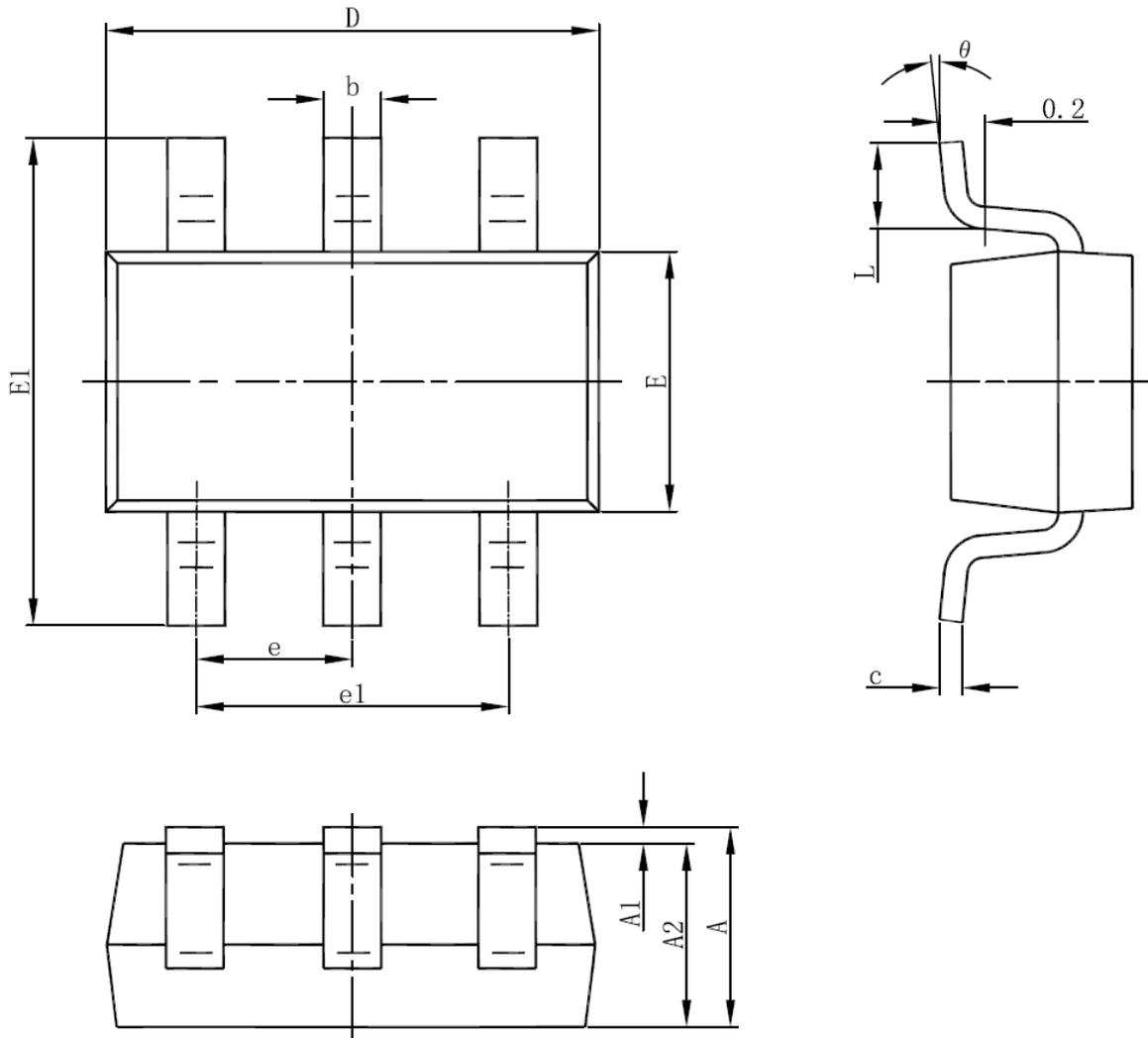


Figure 14 Normalized Maximum Transient Thermal Impedance

SOT23-6L PACKAGE INFORMATION



| Symbol | Dimensions In Millimeters | | Dimensions In Inches | |
|--------|---------------------------|-------|----------------------|-------|
| | Min | Max | Min | Max |
| A | 1.050 | 1.250 | 0.041 | 0.049 |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 |
| A2 | 1.050 | 1.150 | 0.041 | 0.045 |
| b | 0.300 | 0.500 | 0.012 | 0.020 |
| c | 0.100 | 0.200 | 0.004 | 0.008 |
| D | 2.820 | 3.020 | 0.111 | 0.119 |
| E | 1.500 | 1.700 | 0.059 | 0.067 |
| E1 | 2.650 | 2.950 | 0.104 | 0.116 |
| e | 0.950(BSC) | | 0.037(BSC) | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 |
| L | 0.300 | 0.600 | 0.012 | 0.024 |
| theta | 0° | 8° | 0° | 8° |